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This section provides packaging information for the Stratix® III device.

- [Chapter 17, Stratix III Device Packaging Information](#)

### Revision History

Refer to each chapter for its own specific revision history. For information on when each chapter was updated, refer to the Chapter Revision Dates section, which appears in the full handbook.



## Introduction

This chapter provides package information for Altera® Stratix® III devices, including:

- Device and package cross reference
- Thermal resistance values
- Package outlines

Table 17–1 shows which Stratix III devices, are available in FineLine BGA (FBGA) packages.

**Table 17–1.** Stratix III Devices in FBGA Packages

Device	Package	Pins
EP3SL50	FineLine BGA - Flip Chip	484
	FineLine BGA - Flip Chip	780
EP3SL70	FineLine BGA - Flip Chip	484
	FineLine BGA - Flip Chip	780
EP3SL110	FineLine BGA - Flip Chip	780
	FineLine BGA - Flip Chip	1152
EP3SL150	FineLine BGA - Flip Chip	780
	FineLine BGA - Flip Chip	1152
EP3SL200	Hybrid FineLine BGA - Flip Chip	780
	FineLine BGA - Flip Chip	1152
	FineLine BGA - Flip Chip	1517
EP3SL340	Hybrid FineLine BGA - Flip Chip	1152
	FineLine BGA - Flip Chip	1517
	FineLine BGA - Flip Chip	1760
EP3SE50	FineLine BGA - Flip Chip	484
	FineLine BGA - Flip Chip	780
EP3SE80	FineLine BGA - Flip Chip	780
	FineLine BGA - Flip Chip	1152
EP3SE110	FineLine BGA - Flip Chip	780
	FineLine BGA - Flip Chip	1152
EP3SE260	Hybrid FineLine BGA - Flip Chip	780
	FineLine BGA - Flip Chip	1152
	FineLine BGA - Flip Chip	1517

## Thermal Resistance

For thermal resistance specifications for Stratix III devices, refer to the *Stratix Series Device Thermal Resistance Data Sheet*.

## Package Outlines

You can download Stratix III device package outlines from the *Device Packaging Specifications* web page.

## Chapter Revision History

Table 17-2 shows the revision history for this chapter.

**Table 17-2.** Chapter Revision History

Date and Revision	Changes Made	Summary of Changes
February 2009, version 1.6	Removed “Referenced Documents” section.	—
October 2008, version 1.5	Updated New Document Format.	—
May 2008, version 1.4	Updated “Package Outlines” section hyperlink.	—
November 2007, version 1.3	Updated Table 17-1.	Minor update.
October 2007, version 1.2	<ul style="list-style-type: none"> <li>■ Added new section “Referenced Documents”.</li> <li>■ Added live links for references.</li> </ul>	Minor update.
May 2007, version 1.1	Removed thermal resistance and package outline information and replaced with links referencing this information.	Minor update.
November 2006, version 1.0	Initial Release.	—